LatticeMico System Software Release Notes for Lattice Diamond 3.2

The LatticeMico System Software includes changes to the Lattice Mico System Builder (MSB) and Software Project Environment (C/C++ SPE) for Lattice Diamond® version 3.2.

What's New in LatticeMico System

The following updates are in this version of LatticeMico System software:

▶ Support added for ECP5, MachXO3L, and Platform Manager 2 devices.

▶ EFB (v1.6) component updated to support the MachoXO3L and Platform Manager 2 device families, in addition to MachXO2.

▶ VID (v1.1) component updated as follows:

    ▶ Added WAIT_COUNT parameter to add a wait state between each successive VID transactions.

    ▶ Improved the hardware protect capability in the VID Master Mode.

    ▶ Fixed VID Write Status Register issue.

▶ Updates to following documents:

    ▶ LatticeMico8 Developer User Guide

    ▶ LatticeMico32 Tutorial

    ▶ LatticeMico32 Hardware Developer User Guide

    ▶ LatticeMico32 Software Developer User Guide

Release Compatibility

LatticeMico System Builder platforms developed prior to the release of Lattice Diamond 1.1 (or ispLEVER 8.1 SP1) may need to be analyzed and subsequently updated. Users who open a platform containing one of the components listed below, at the version shown or older, will be given the option to update the platform:

SPI Flash v3.5	SDRAM controller v3.8
DMA v3.1	GPIO v3.4
UART v3.4	Fault Logger v1.0
GPIO v3.1	EFB v1.4

Users who choose to update a platform with a newer version of these components may need to make modifications to their C/C++ source code.It may also be necessary to update any RTL source code instantiating the LatticeMico System Software generated platform.

To get an understanding of how the newer version of these components affects the C/C++ and RTL code please read LatticeMico32 Technical Note 1221. It has a complete description of the changes made, the situations where there will be an impact your existing design, and instructions on how to update your design if it is required.

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